

HOSTAFORM® XGC10 EF XAP®2

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Hostaform® XGC10 EF XAP®2 is an easy flowing injection molding grade reinforced with approximately 10% glass fibers, and has reduced emissions.

Emissions according to VDA 275 < 5 ppm [mg/kg].

Product information

Resin Identification	POM-GF10	ISO 1043
Part Marking Code	>POM-GF10<	ISO 11469

Rheological properties

Melt volume-flow rate	12 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.0 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.1 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	4900 MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	110 MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	4 %	ISO 527-1/-2
Flexural modulus	4700 MPa	ISO 178
Charpy impact strength, 23 °C	60 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23 °C	6.5 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30 °C	6.5 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.35 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10 °C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	154 °C	ISO 75-1/-2

Flammability

Burning rate, Thickness 1 mm	81 mm/min	ISO 3795 (FMVSS 302)
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Physical/Other properties

Density	1480 kg/m ³	ISO 1183
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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C

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Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa
Ejection temperature	138 °C

Characteristics

Processing	Injection Moulding
Special characteristics	High Flow, Low emissions

Automotive

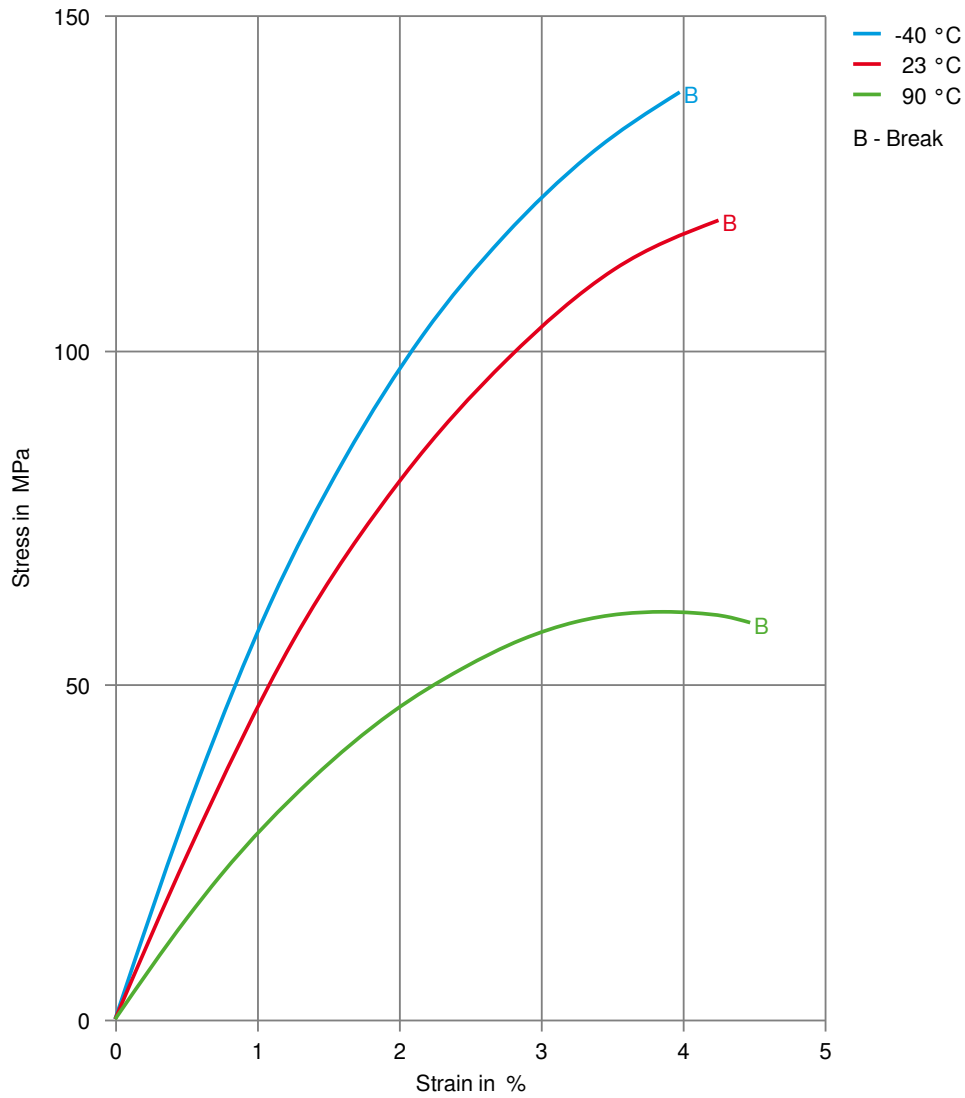
OEM
VW Group

ADDITIONAL INFORMATION
No Spec, Special Part Approval, See Your CE
Account Manager.

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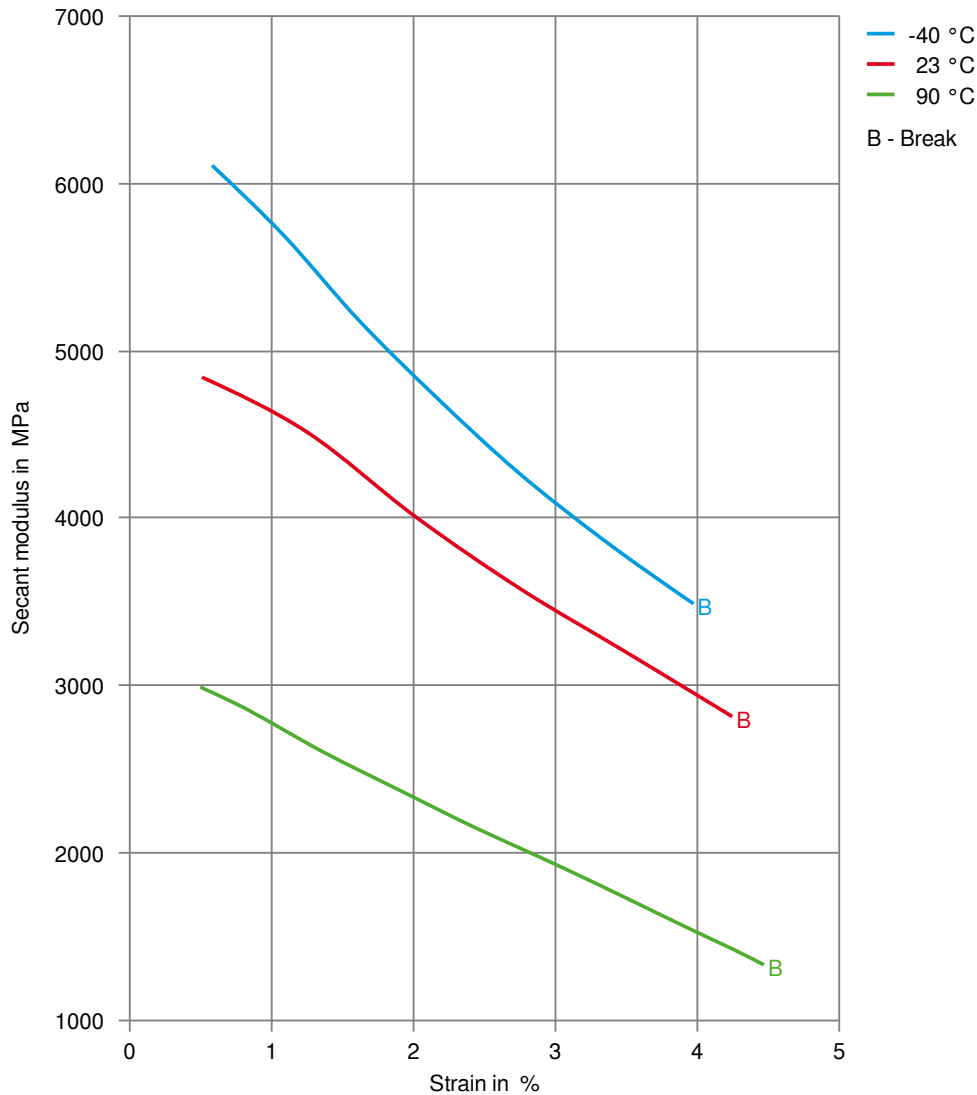
Stress-strain



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Secant modulus-strain



Printed: 2025-03-27

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Revised: 2024-07-12 Source: Celanese Materials Database

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